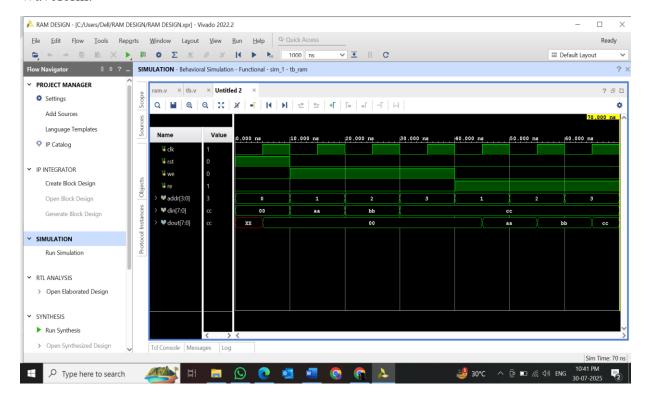
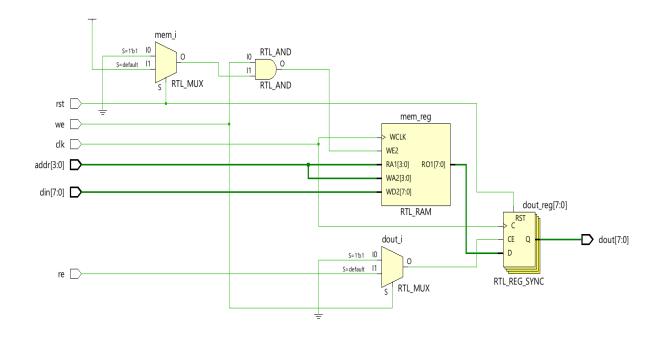
RAM DESIGN:

Waveform:



Elaborated Design:



Reports:

Summary

Power analysis from Implemented netlist. Activity derived from constraints files, simulation files or vectorless analysis.

Total On-Chip Power: 0.76 W

Design Power Budget: Not Specified

Power Budget Margin: N/A
Junction Temperature: 26.4°C

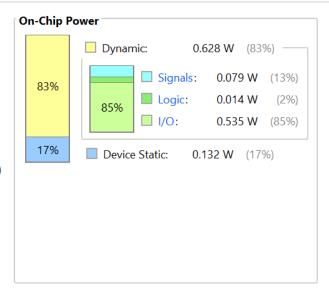
Thermal Margin: 58.6°C (31.0 W)

Effective ϑJA : 1.9°C/W

Power supplied to off-chip devices: 0 W Confidence level:

Launch Power Constraint Advisor to find and fix

invalid switching activity



Name 1	Slice LUTs (134600)	Slice Registers (269200)	Slice (33650)	LUT as Logic (134600)	LUT as Memory (46200)	Bonded IOB (400)	BUFGCTRL (32)
N ram	10	8	3	2	8	24	1

Name	Port	I/O Std	Vcco	Slew	Drive Strength (Off-Chip Termina	Remaining Margin	Notes
% I/O Bank 0 (0)								
≫ I/O Bank 12 (0)								
≫ I/O Bank 13 (0)								
I/O Bank 14 (8)		LVCMOS18	1.80	SLOW	12	FP_VTT_50		
▶ P24	dout[0]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
▶ P23	dout[1]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
№ N19	dout[2]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
▶ P19	dout[3]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
№ N24	dout[4]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
№ N23	dout[5]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
▶ P21	dout[6]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
▶ P20	dout[7]	LVCMOS18	1.80	SLOW	12	FP_VTT_50	85.19	
% I/O Bank 15 (0)								
% I/O Bank 16 (0)								
% I/O Bank 33 (0)								
% I/O Bank 34 (0)								
Љ I/O Bank 35 (0)								

Design Timing Summary

Setup		Hold		Pulse Width		
Worst Negative Slack (WNS):	inf	Worst Hold Slack (WHS):	inf	Worst Pulse Width Slack (WPWS):	NA	
Total Negative Slack (TNS):	0.000 ns	Total Hold Slack (THS):	0.000 ns	Total Pulse Width Negative Slack (TPWS):	NA	
Number of Failing Endpoints:	0	Number of Failing Endpoints:	0	Number of Failing Endpoints:	NA	
Total Number of Endpoints:	80	Total Number of Endpoints:	80	Total Number of Endpoints:	NA	

There are no user specified timing constraints.